



NXT-DS Pd Gen3

Highly optimized dual plating configuration

Linxens NXT-DS Pd Gen3 is a combination of dual NXT products with Palladium feature for higher differentiation.

Key Features

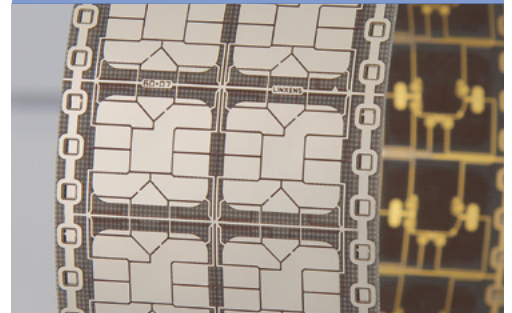
- Optimized dual solution
- Worldwide reference plating family
- High corrosion resistance
- Dual version of the Palladium Gen3

Typical Product Designs

Part Number	Modules	Cavity	Chip Dimension
9X36008	8	No	4.1 x 3.9 mm
9X33217	8	No	4.1 x 6.4 mm



MICROCONNECTORS



Overview

Material

- Film base: Copper-clad epoxy glass
- Adhesive: High temperature modified Epoxy MCHT
- Copper: ED29 μ

Thickness

- Total: 203 \pm 20 μ m / 209 \pm 20 μ m
- Plating Thickness):
 - Contact side:
 - Ni: 2.0 (-0.6 +1.0) μ m
 - Au: Gold flash
 - Pd: 0.10 \pm 0.05 μ m
 - Back side:
 - Ni: 5.0 (-2.0 +5.0) μ m
 - Au: 0.3 (-0.1 +0.6) μ m

Temperature Resistance

- 3 minutes at 260°C
- 21 hours at 160°C

Plating Performance

Corrosion resistance: High
Chemical resistance: High

Compliance Labels

- ISO 10373
- ISO 7810

Application Area

- Financial services

Options

- Fully-etched / Micro-etched
- Colored tape: Red, blue, orange